ABSTRACT

SUBSTRATE CARRIER FOR MOLDING ELECTRONIC DEVICES

A method of molding a substrate containing a plurality of electronic devices by providing a carrier comprising a frame which includes an adhesive film. The substrate is mounted onto the adhesive film of the carrier such that the frame surrounds the substrate. The carrier is placed in a mold such that the frame is located at a clamping area of the mold and the substrate is located at a molding area of the mold where molding cavities are located. The frame is clamped at the clamping area while the electronic devices are located in the molding cavities for molding with an encapsulant.

(FIG. 8)